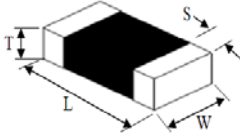
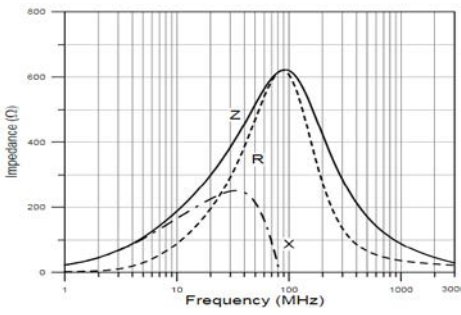
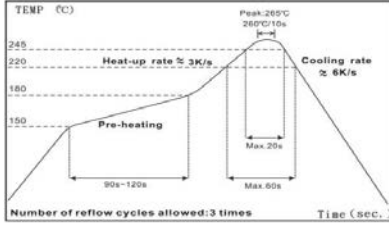
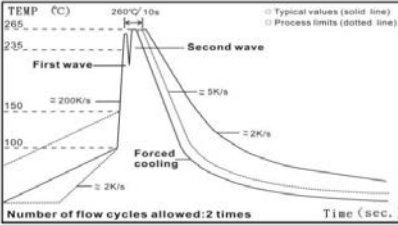


## SPECIFICATION FOR APPROVAL

Multilayer Chip Bead – <b>FBM1206</b> Type		Issue No.
Customer :		Issue Day. <b>24/03/2021</b>
Part No. <b>FBM1206ST601S</b>	Impedance : <b>600 Ω</b>	Tolerance : <b>±25 %</b>
Rated Current : <b>350 mA</b>	DCR (Max.) : <b>0.25 Ω</b>	Test Frequency : <b>100 MHz</b>
Diagram of Dimensions : (Unit : mm)		
		<p>L : <u>3.20 ±0.20</u></p> <p>W : <u>1.60 ±0.20</u></p> <p>T : <u>1.60 ±0.20</u></p> <p>S : <u>0.20 ~ 1.00</u></p>
Specification & Test Method		
1	Operating Temperature Range : -55°C ~ +125°C	
2	Solderability :Pre-heating:150°C,1min / Solder Temperature :245±5°C/Immersion Time: 4±1sec	
3	Impedance measured in HP4291B	
4	DCR measured in Agilent 34401A	
5	Typical Impedance vs. Frequency Range	
		
6	Soldering Profile :	
<div style="display: flex; justify-content: space-around;"> <div style="text-align: center;"> <p><b>Reflow Soldering</b></p>  </div> <div style="text-align: center;"> <p><b>Wave Soldering</b></p>  </div> </div>		
<p>(1) Time of IR reflow soldering at maximum temperature point 260°C : 10s</p> <p>(2) Time of wave soldering at maximum temperature point 260°C : 10s</p> <p>(3) Time of soldering iron at maximum temperature point 410°C : 5s</p>		
<b>APPROVED BY CUSTOMER</b>		<b>REMARK :</b>
<p>Your Confirmation :</p> <p><input type="checkbox"/> Approval</p> <p><input type="checkbox"/> Conditional Approval</p> <p><input type="checkbox"/> Rejection</p> <p>(Please send a copy for our ref.)</p>		<p>For further details please visit the following link of our website:</p> <p><a href="#"><b>FBM_20170331.pdf</b></a></p>
Inspected by		Checked by
		吳美華
Approved by		許介洲